CLAIM AMENDMENTS

Please cancel claims 1-10 and 21-23 and amend claims 14, 15, 16 as follows:

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)
5. (Cancelled)
6. (Cancelled)
7. (Cancelled)
8. (Cancelled)
9. (Cancelled)
10. (Cancelled)

11. (Previously Amended) A pressure transducer, comprising:

a carrier having a central aperture for receiving fluid from a vessel;

a sense die mounted on the carrier, the sense die having a first side positioned to interact with the fluid received from the vessel;

pressure-sensing circuitry formed on a second side of the sense die note exposed to the fluid;

a ceramic board mounted on the carrier, the ceramic board bearing conductive paths electrically connecting the pressure-sensing circuitry to external circuitry; and

at least a first and a second layer, wherein the first layer includes at least a first conductive path electrically connected to at least the pressure-sensing circuitry, and the second layer includes at least a second conductive path in contact with the first conductive path.

12. (Original) The pressure transducer of claim 11, wherein the first and second conductive paths are formed within the ceramic board and have a first set of contacts for electrically connecting to the pressure-sensing circuitry and a second set of contacts for electrically connecting to the external circuitry.

13. (Previously Cancelled)

14. (Currently Amended) The pressure transducer of claim 12 ~~13~~, wherein the second conductive path electrically connects to the external circuitry.

15. (Original) The pressure transducer of claim 12 ~~13~~, wherein the first conductive path electrically connects to the external circuitry.

16. (Currently Amended) The pressure transducer of claim 12 ~~13~~, wherein the first conductive path passes from one side of the first layer to an opposite side, and the second conductive path is formed along a surface of the second layer.

17. (Original) The pressure transducer of claim 16, wherein the first layer is secured to the second layer, the second conductive path being contained between the first layer and the second layer.

18. (Previously Amended) The pressure transducer of claim 11, further comprising:

a non-metal cover positioned to prevent the fluid or other external elements from contacting the second side of the sense die, and hermetically-sealed.

19. (Original) The pressure transducer of claim 11, wherein the carrier is mounted within a housing positioned and configured to confine fluid entering the housing to the central aperture.

20. (Original) The pressure transducer of claim 19 further comprising:

a lid hermetically-sealed to an access opening to the containment area of the housing.

21. (Cancelled)
22. (Cancelled)
23. (Cancelled)